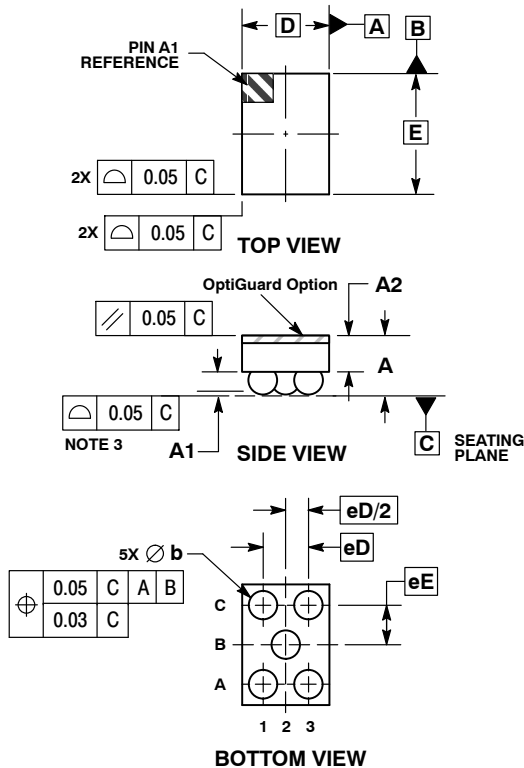




SCALE 4:1

WLCSP5, 0.96x1.33  
CASE 567AY  
ISSUE O

DATE 26 JUL 2010

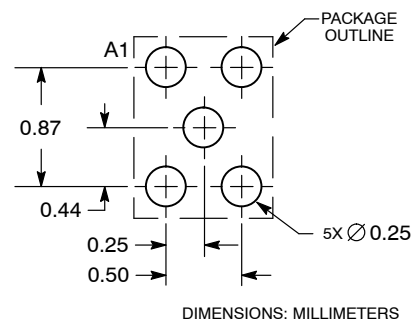


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	0.56	0.72
A1	0.21	0.27
A2	0.40	REF
b	0.29	0.35
D	0.96	BSC
E	1.33	BSC
eD	0.50	BSC
eE	0.435	BSC

RECOMMENDED  
SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP5, 0.96X1.33	PAGE 1 OF 1

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